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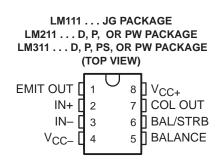
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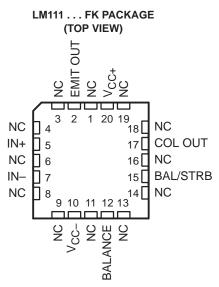
Jameco Part Number 1344454

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- Fast Response Times
- Strobe Capability
- Maximum Input Bias Current . . . 300 nA
- Maximum Input Offset Current . . . 70 nA



- Can Operate From Single 5-V Supply
- Available in Q-Temp Automotive
 High-Reliability Automotive Applications
 - Configuration Control/Print Support
 - Qualification to Automotive Standards



NC - No internal connection

description/ordering information

The LM111, LM211, and LM311 are single high-speed voltage comparators. These devices are designed to operate from a wide range of power-supply voltages, including \pm 15-V supplies for operational amplifiers and 5-V supplies for logic systems. The output levels are compatible with most TTL and MOS circuits. These comparators are capable of driving lamps or relays and switching voltages up to 50 V at 50 mA. All inputs and outputs can be isolated from system ground. The outputs can drive loads referenced to ground, V_{CC+} or V_{CC-}. Offset balancing and strobe capabilities are available, and the outputs can be wire-OR connected. If the strobe is low, the output is in the off state, regardless of the differential input.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.



Copyright © 2003, Texas Instruments Incorporated On products compliant to MIL-PRF-38535, all parameters are tested unless otherwise noted. On all other products, production processing does not necessarily include testing of all parameters.

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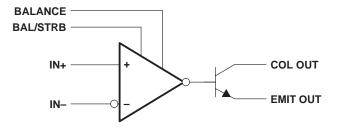
description/ordering information

Τ _Α	V _{IO} max AT 25°C	PACKAGE [†]		ORDERABLE PART NUMBER	TOP-SIDE MARKING
		PDIP (P)	Tube of 50	LM311P	LM311P
		SOIC (D)	Tube of 75	LM311D	LM311
–0°C to 70°C	7.5 mV	3010 (D)	Reel of 2500	LM311DR	
-0 C 10 70 C	7.5 111	SOP (PS)	Reel of 2000	LM311PSR	L311
		TSSOP (PW)	Reel of 150	LM311PW	L311
		1330F (FW)	Tube of 2000	LM311PWR	
		PDIP (P)	Tube of 50	LM211P	LM211P
			SOIC (D)	Tube of 75	LM211D
–40°C to 85°C	3 mV	3010 (D)	Reel of 2500	LM211DR	
		TSSOP (PW)	Reel of 150	LM211PW	L211
		1330F (FW)	Reel of 2000	LM211PWR	
–40°C to 125°C	3 mV	SOIC (D)	Tube of 75	LM211QD	LM211Q
-40 C to 125 C	5 1117		Reel of 2500	LM211QDR	
–55°C to 125°C	3 mV	CDIP (JG)	Tube of 50	LM111JG	LM111JG
-55°C to 125°C	31117	LCCC (FK)	Tube of 55	LM111FK	LM111FK

ORDERING INFORMATION

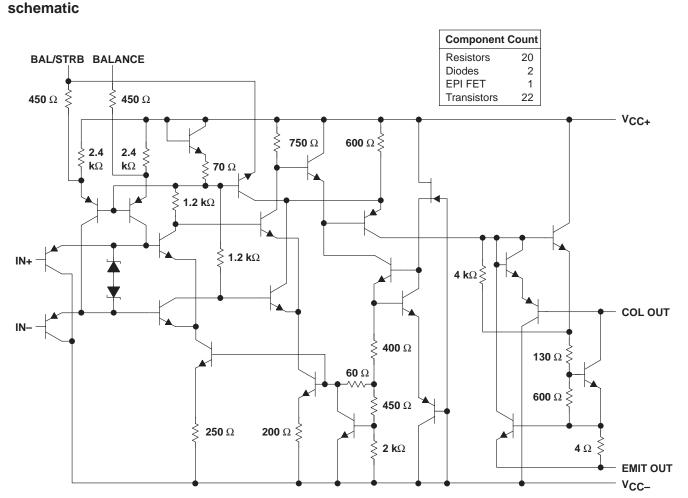
[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

functional block diagram





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All resistor values shown are nominal.



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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage: V _{CC+} (see Note 1)	
V _{CC} (see Note 1)	
$V_{CC+} - V_{CC-}$	
Differential input voltage, VID (see Note 2)	
Input voltage, V _I (either input, see Notes 1 and 3)	±15 V
Voltage from emitter output to V _{CC}	
Voltage from collector output to V _{CC} _: LM111	
	50 V
LM211Q	50 V
LM311	40 V
Duration of output short circuit (see Note 4)	10 s
Package thermal impedance, θ_{JA} (see Notes 5 and 6): D packa	ge 97°C/W
P packa	ge 85°C/W
PS pack	age 95°C/W
PW pac	kage 149°C/W
Package thermal impedance, θ_{JC} (see Notes 7 and 8): FK pack	age 5.61°C/W
JG pack	age 14.5°C/W
Operating virtual junction temperature, T _J	150°C
Case temperature for 60 seconds: FK package	
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds	J or JG package 300°C
Lead temperature 1,6 mm (1/16 inch) from case for 60 seconds	D, P, PS, or PW package 260°C
Storage temperature range, T _{stg}	–65°C to 150°C

⁺ Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. All voltage values, unless otherwise noted, are with respect to the midpoint between V_{CC+} and V_{CC-}.

- 2. Differential voltages are at IN+ with respect to IN-.
- 3. The magnitude of the input voltage must never exceed the magnitude of the supply voltage or ±15 V, whichever is less.
- 4. The output may be shorted to ground or either power supply.
- 5. Maximum power dissipation is a function of T_J(max), θ_{JA} , and T_A. The maximum allowable power dissipation at any allowable ambient temperature is P_D = (T_J(max) T_A)/ θ_{JA} . Operating at the absolute maximum T_J of 150°C can affect reliability.
- 6. The package thermal impedance is calculated in accordance with JESD 51-7.
- 7. Maximum power dissipation is a function of $T_J(max)$, θ_{JC} , and T_C . The maximum allowable power dissipation at any allowable case temperature is $P_D = (T_J(max) T_C)/\theta_{JC}$. Operating at the absolute maximum T_J of 150°C can affect reliability.
- 8. The package thermal impedance is calculated in accordance with MIL-STD-883.

recommended operating conditions

			MIN	MAX	UNIT
V _{CC+} -V _{CC-}	Supply voltage		3.5	30	V
VI	Input voltage ($ V_{CC\pm} \le 15 V$)		V _{CC} _+0.5	V _{CC+} -1.5	V
		LM111	-55	125	
т.	Operating free-air temperature range	LM211	-40	85	°C
TA	Operating nee-air temperature range	LM211Q	-40	125	C
		LM311	0	70	



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electrical characteristics at specified free-air temperature, $V_{CC\pm} = \pm 15$ V (unless otherwise noted)

						<u> </u>					
PARAMETER		TEST CON	TEST CONDITIONS T _A †			LM111 LM211 LM211Q			LM311		UNIT
				MIN	TYP‡	MAX	MIN	TYP‡	MAX		
Vie	Input offset voltage	See Note 6		25°C		0.7	3		2	7.5	mV
VIO	input onset voltage	See Note 0		Full range			4			10	IIIV
IIO	Input offset current	See Note 6		25°C		4	10		6	50	nA
UU	input bilact current			Full range			20			70	
IIB	Input bias current	$V_{O} = 1 V \text{ to } 14 V$		25°C		75	100		100	250	nA
ΊΒ	input bias current	10-110141		Full range			150			300	
I _{IL(S)}	Low-level strobe current (see Note 7)	$V_{(strobe)} = 0.3 V,$	$V_{ID} \leq -10 \text{ mV}$	25°C		-3			-3		mA
VICR	Common-mode input voltage range			Full range	13 to -14.5	13.8 to –14.7		13 to -14.5	13.8 to –14.7		V
AVD	Large-signal differential voltage amplification	$V_{O} = 5 V$ to 35 V,	RL = 1 kΩ	25°C	40	200		40	200		V/mV
	High-level	$I_{(strobe)} = -3 \text{ mA},$	V _{OH} = 35 V,	25°C		0.2	10				nA
ЮН	(collector) output leakage	$V_{ID} = 5 \text{ mV}$	••••	Full range			0.5				μA
	current	V _{ID} = 5 mV,	V _{OH} = 35 V	25°C					0.2	50	nA
		La. 50 m A	V _{ID} = -5 mV	25°C		0.75	1.5				
	Low-level	I _{OL} = 50 mA	$V_{ID} = -10 \text{ mV}$	25°C					0.75	1.5	
VOL	(collector-to-emitter) output voltage	V _{CC+} = 4.5 V,	$V_{ID} = -6 \text{ mV}$	Full range		0.23	0.4				V
	ouiput voltage	V _{CC} -= 0, I _{OL} = 8 mA	V _{ID} = -10 mV	Full range					0.23	0.4	
ICC+	Supply current from V _{CC+} , output low	V _{ID} = -10 mV,	No load	25°C		5.1	6		5.1	7.5	mA
ICC-	Supply current from V _{CC} , output high	V _{ID} = 10 mV,	No load	25°C		-4.1	-5		-4.1	-5	mA

[†] Unless otherwise noted, all characteristics are measured with BALANCE and BAL/STRB open and EMIT OUT grounded.

Full range for LM111 is -55°C to 125°C, for LM211 is -40°C to 85°C, for LM211Q is -40°C to 125°C, and for LM311 is 0°C to 70°C.

[‡] All typical values are at $T_A = 25^{\circ}C$.

NOTES: 9. The offset voltages and offset currents given are the maximum values required to drive the collector output up to 14 V or down to 1 V with a pullup resistor of 7.5 kΩ to V_{CC+}. These parameters actually define an error band and take into account the worst-case effects of voltage gain and input impedance.

10. The strobe should not be shorted to ground; it should be current driven at -3 mA to -5 mA (see Figures 13 and 27).

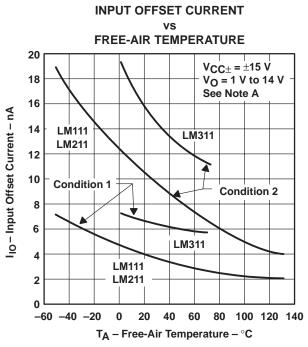
switching characteristics, V_{CC\pm} = ± 15 V, T_A = 25°C

PARAMETER		TEST CONDITIONS	TEST CONDITIONS			
				ТҮР		
Response time, low-to-high-level output	$B_{0} = 500 \Omega to 5 V$		See Note 8	115	ns	
Response time, high-to-low-level output	R_{C} = 500 Ω to 5 V,	C _L = 5 pF,	See Note o	165	ns	

NOTE 11: The response time specified is for a 100-mV input step with 5-mV overdrive and is the interval between the input step function and the instant when the output crosses 1.4 V.



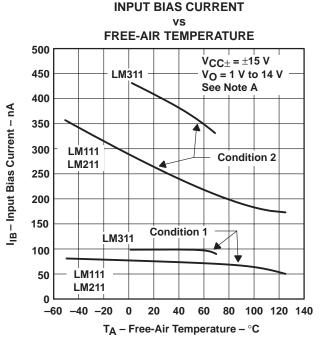
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TYPICAL CHARACTERISTICS[†]

NOTE A: Condition 1 is with BALANCE and BAL/STRB open. Condition 2 is with BALANCE and BAL/STRB connected to V_{CC+} .

Figure 1



NOTE A: Condition 1 is with BALANCE and BAL/STRB open. Condition 2 is with BALANCE and BAL/STRB connected to V_{CC+}.

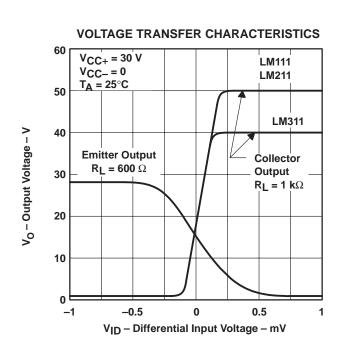
Figure 2

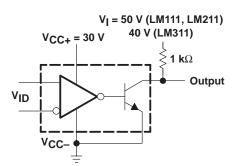
[†] Data at high and low temperatures are applicable only within the rated operating free-air temperature ranges of the various devices.



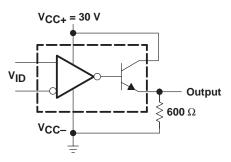
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TYPICAL CHARACTERISTICS[†]





COLLECTOR OUTPUT TRANSFER CHARACTERISTIC TEST CIRCUIT FOR FIGURE 3



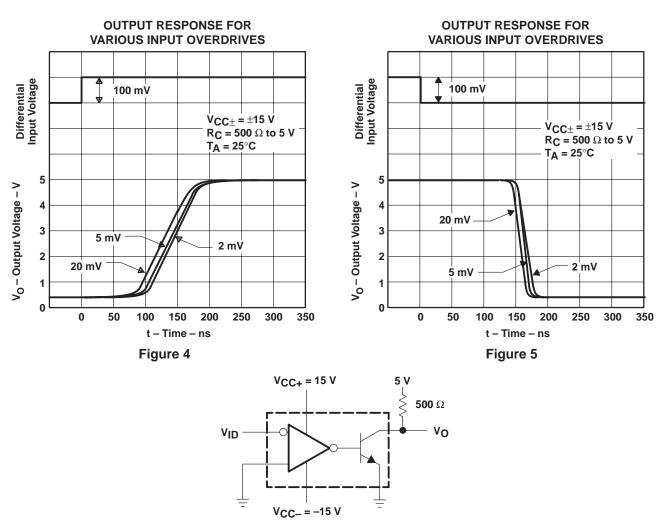
EMITTER OUTPUT TRANSFER CHARACTERISTIC TEST CIRCUIT FOR FIGURE 3

Figure 3

[†] Data at high and low temperatures are applicable only within the rated operating free-air temperature ranges of the various devices.



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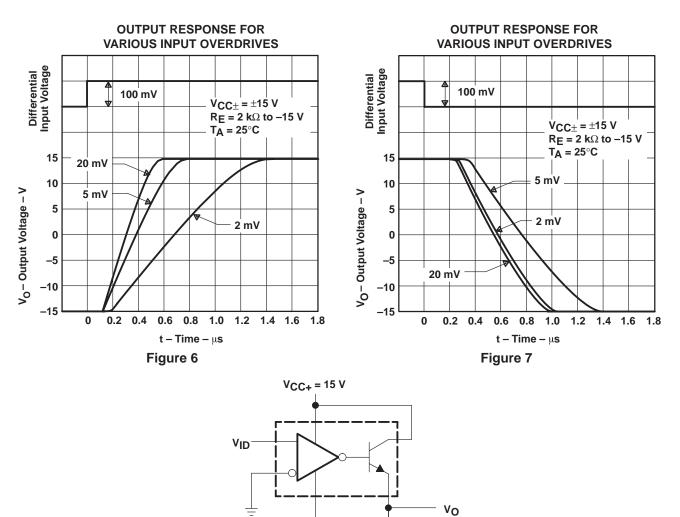


TYPICAL CHARACTERISTICS

TEST CIRCUIT FOR FIGURES 4 AND 5



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 $R_E = 2 k\Omega$

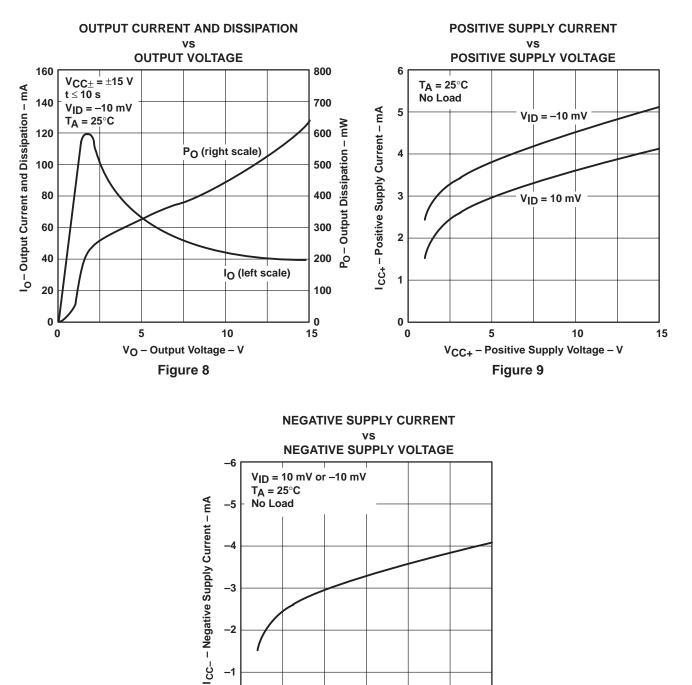
TYPICAL CHARACTERISTICS



 $V_{CC-} = -15 V$

TEST CIRCUIT FOR FIGURES 6 AND 7

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TYPICAL CHARACTERISTICS



-5

V_{CC}-- Negative Supply Voltage -- V

Figure 10

-10

-15

-1

0 0

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APPLICATION INFORMATION

Figure 11 through Figure 29 show various applications for the LM111, LM211, and LM311 comparators.

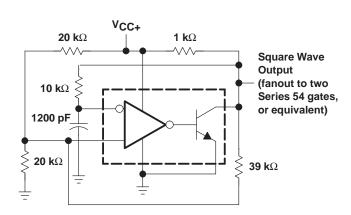
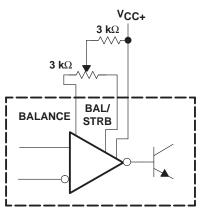
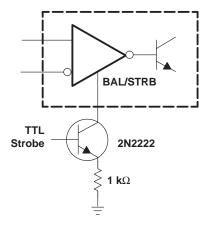


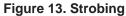
Figure 11. 100-kHz Free-Running Multivibrator



NOTE: If offset balancing is not used, the BALANCE and BAL/STRB pins should be shorted together.

Figure 12. Offset Balancing





NOTE: Do not connect strobe pin directly to ground, because the output is turned off whenever current is pulled from the strobe pin.

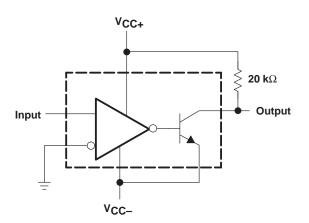
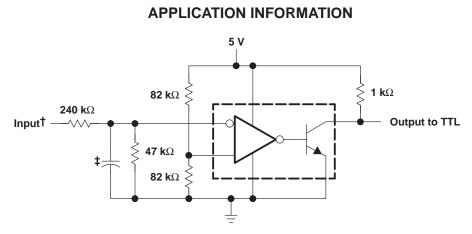


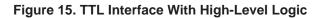
Figure 14. Zero-Crossing Detector



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[†] Resistor values shown are for a 0- to 30-V logic swing and a 15-V threshold.
 [‡] May be added to control speed and reduce susceptibility to noise spikes



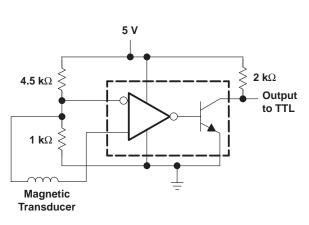
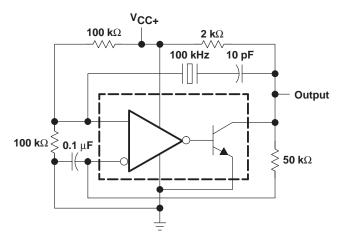
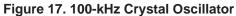


Figure 16. Detector for Magnetic Transducer







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APPLICATION INFORMATION

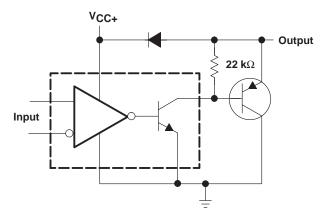
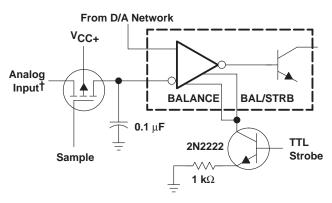


Figure 18. Comparator and Solenoid Driver



[†] Typical input current is 50 pA with inputs strobed off.

Figure 19. Strobing Both Input and Output Stages Simultaneously

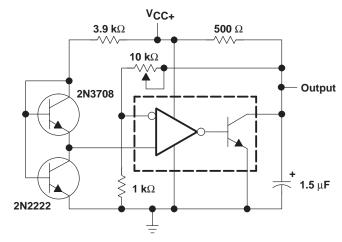


Figure 20. Low-Voltage Adjustable Reference Supply

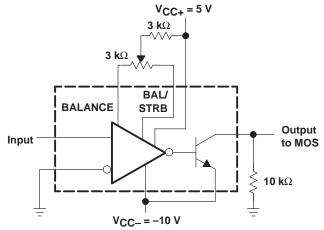
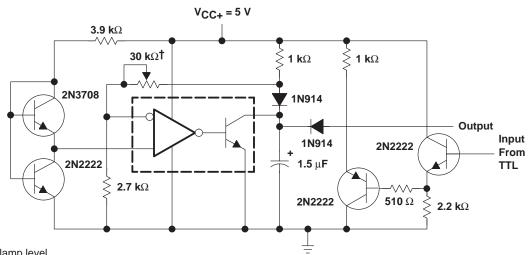


Figure 21. Zero-Crossing Detector Driving MOS Logic



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APPLICATION INFORMATION

[†] Adjust to set clamp level

Figure 22. Precision Squarer

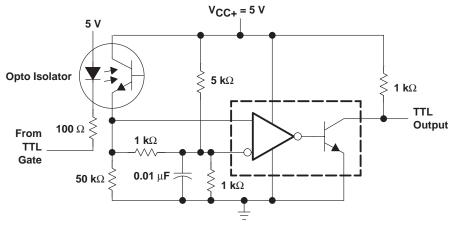


Figure 23. Digital Transmission Isolator

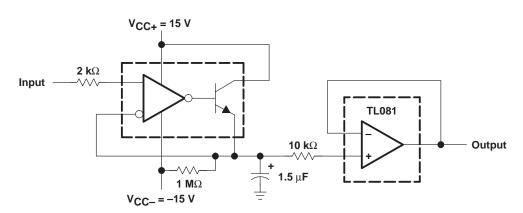


Figure 24. Positive-Peak Detector



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APPLICATION INFORMATION

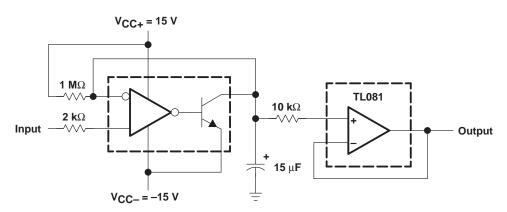
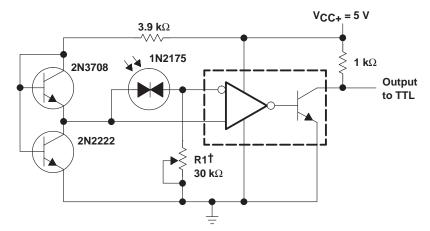
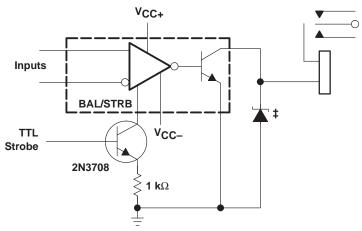


Figure 25. Negative-Peak Detector



[†]R1 sets the comparison level. At comparison, the photodiode has less than 5 mV across it, decreasing dark current by an order of magnitude.

Figure 26. Precision Photodiode Comparator

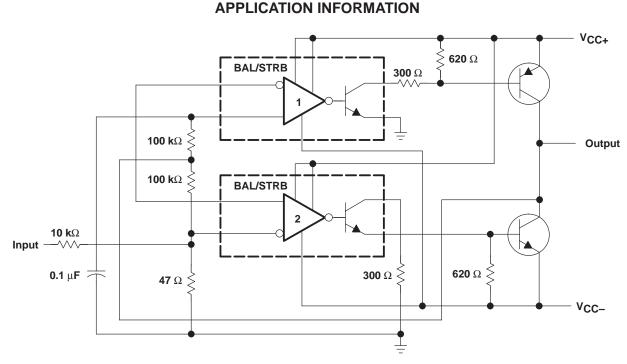


[‡] Transient voltage and inductive kickback protection





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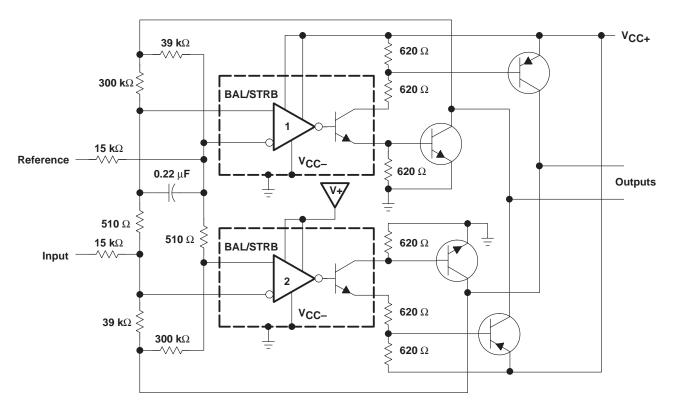


Figure 29. Switching Power Amplifiers



9-Oct-2007

PACKAGING INFORMATION

Orderable Devic	e Status ⁽¹⁾	Package Type	Package Drawing	Pins	Packag Qty	e Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
JM38510/10304BI	PA ACTIVE	CDIP	JG	8	1	TBD	A42 SNPB	N / A for Pkg Type
LM111FKB	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
LM111JG	ACTIVE	CDIP	JG	8	1	TBD	A42 SNPB	N / A for Pkg Type
LM111JGB	ACTIVE	CDIP	JG	8	1	TBD	A42 SNPB	N / A for Pkg Type
LM211D	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
LM211DE4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
LM211DG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
LM211DR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
LM211DRE4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
LM211DRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
LM211P	ACTIVE	PDIP	Р	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
LM211PE4	ACTIVE	PDIP	Р	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
LM211PW	ACTIVE	TSSOP	PW	8	150	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
LM211PWE4	ACTIVE	TSSOP	PW	8	150	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
LM211PWG4	ACTIVE	TSSOP	PW	8	150	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
LM211PWR	ACTIVE	TSSOP	PW	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
LM211PWRE4	ACTIVE	TSSOP	PW	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
LM211PWRG4	ACTIVE	TSSOP	PW	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
LM211QD	NRND	SOIC	D	8	75	Pb-Free (RoHS)	CU NIPDAU	Level-2-250C-1 YEAR/ Level-1-235C-UNLIM
LM211QDG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
LM211QDR	NRND	SOIC	D	8	2500	Pb-Free (RoHS)	CU NIPDAU	Level-2-250C-1 YEAR/ Level-1-235C-UNLIM
LM211QDRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
LM311D	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
LM311DE4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
LM311DG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
LM311DR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
LM311DRE4	ACTIVE	SOIC	D	8	2500	Green (RoHS &	CU NIPDAU	Level-1-260C-UNLIM



Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Packag Qty	e Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
						no Sb/Br)		
LM311DRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
LM311P	ACTIVE	PDIP	Р	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
LM311PE4	ACTIVE	PDIP	Р	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
LM311PSR	ACTIVE	SO	PS	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
LM311PSRE4	ACTIVE	SO	PS	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
LM311PSRG4	ACTIVE	SO	PS	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
LM311PW	ACTIVE	TSSOP	PW	8	150	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
LM311PWE4	ACTIVE	TSSOP	PW	8	150	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
LM311PWG4	ACTIVE	TSSOP	PW	8	150	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
LM311PWLE	OBSOLETE	TSSOP	PW	8		TBD	Call TI	Call TI
LM311PWR	ACTIVE	TSSOP	PW	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
LM311PWRE4	ACTIVE	TSSOP	PW	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
LM311PWRG4	ACTIVE	TSSOP	PW	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
LM311Y	OBSOLETE	DIESALE	Y	0		TBD	Call TI	Call TI

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

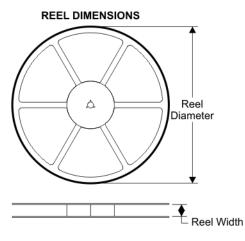
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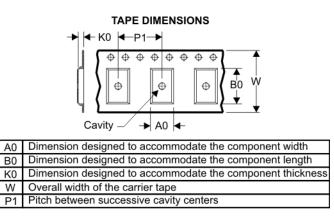


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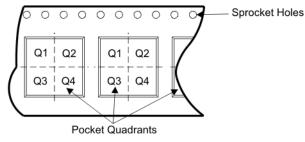
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TAPE AND REEL BOX INFORMATION





QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE

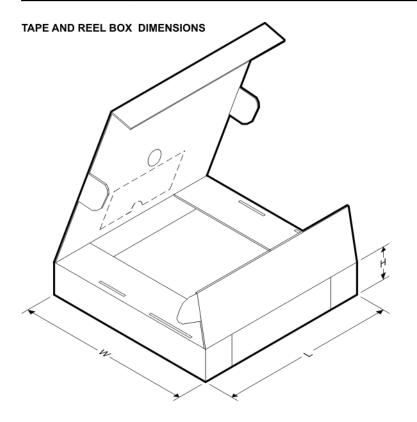


Device	Package	Pins	Site	Reel Diameter (mm)	Reel Width (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
LM211DR	D	8	SITE 27	330	12	6.4	5.2	2.1	8	12	Q1
LM211DR	D	8	SITE 41	330	12	6.4	5.2	2.1	8	12	Q1
LM211PWR	PW	8	SITE 41	330	12	7.0	3.6	1.6	8	12	Q1
LM311DR	D	8	SITE 27	330	12	6.4	5.2	2.1	8	12	Q1
LM311DR	D	8	SITE 41	330	12	6.4	5.2	2.1	8	12	Q1
LM311PSR	PS	8	SITE 41	330	16	8.2	6.6	2.5	12	16	Q1
LM311PWR	PW	8	SITE 41	330	12	7.0	3.6	1.6	8	12	Q1



PACKAGE MATERIALS INFORMATION

12-Jan-2008



Device	Package	Pins	Site	Length (mm)	Width (mm)	Height (mm)
LM211DR	D	8	SITE 27	342.9	338.1	20.64
LM211DR	D	8	SITE 41	346.0	346.0	29.0
LM211PWR	PW	8	SITE 41	346.0	346.0	29.0
LM311DR	D	8	SITE 27	342.9	338.1	20.64
LM311DR	D	8	SITE 41	346.0	346.0	29.0
LM311PSR	PS	8	SITE 41	346.0	346.0	33.0
LM311PWR	PW	8	SITE 41	346.0	346.0	29.0

MECHANICAL DATA

MCER001A - JANUARY 1995 - REVISED JANUARY 1997



CERAMIC DUAL-IN-LINE



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification.
- E. Falls within MIL STD 1835 GDIP1-T8



MLCC006B - OCTOBER 1996

FK (S-CQCC-N**)

LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a metal lid.
- D. The terminals are gold plated.
- E. Falls within JEDEC MS-004



MECHANICAL DATA

MPDI001A - JANUARY 1995 - REVISED JUNE 1999



- NOTES: A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. Falls within JEDEC MS-001

For the latest package information, go to http://www.ti.com/sc/docs/package/pkg_info.htm



D (R-PDSO-G8)

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 (0,15) per end.

Body width does not include interlead flash. Interlead flash shall not exceed .017 (0,43) per side.

E. Reference JEDEC MS-012 variation AA.



MECHANICAL DATA

PS (R-PDSO-G8)

PLASTIC SMALL-OUTLINE PACKAGE



A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



MECHANICAL DATA

MTSS001C - JANUARY 1995 - REVISED FEBRUARY 1999

PW (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

14 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
- D. Falls within JEDEC MO-153



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